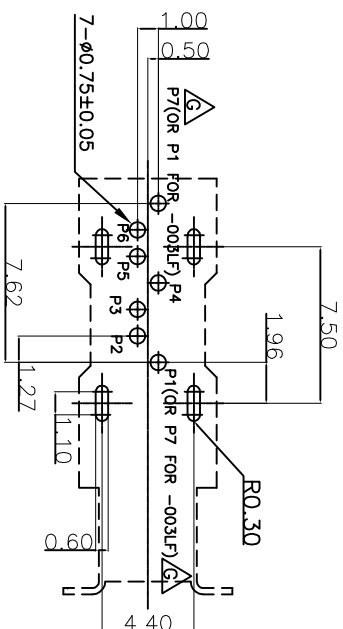
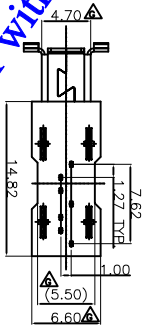
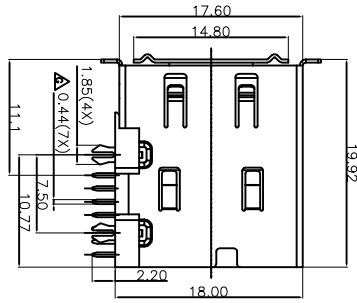
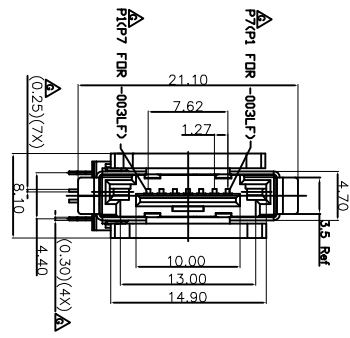


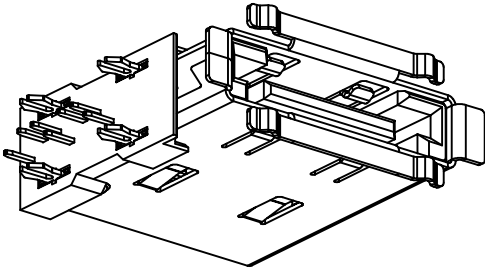
PRODUCT NO.  
10074141-001LF  
10074141-003LF



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RECOMMEND P.C.B.O.A.R.D. LAYOUT  
PCB TOLERANCE:±0.05

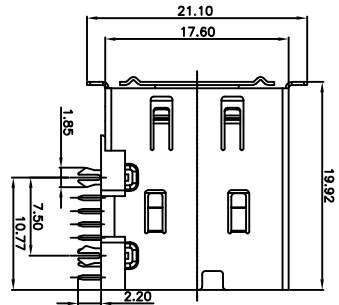
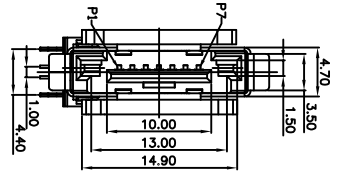
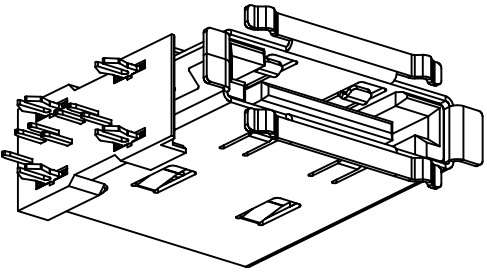
- NOTES:
1. MATERIAL: HOUSING:THERMAL/PLASTIC HIGH TEMP WITH 30% G/F U194 V-0
  2. FINISH: 500" MIN. NICKEL UNDERPLATING OVER ALL SHELL/BOARD LOOK:500" MIN. NICKEL PLATING OVER ALL IN A WAVE SOLDER APPLICATION WITH A 15MM PCB
  3. THE HOUSING WILL WITHSTAND TO 280C FOR 10 SEC
  4. PRODUCT SPEC : GS-12-386
  5. PACKING SPEC : GS-14-1109
  6. A SYMBOL  $\Delta$  WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION
- PACKING: TRAY PACKING  
BLANK: TRAY PACKING  
1. 150" GOLD PLATING  
2. 2 G/F GOLD PLATING  
3. 150" GOLD PLATING WITH NEW PINOUT ASSIGNMENT



PIN DEFINITION

ESATA	NAME	TYPE
P1	GND	GND
P2	A+	A+
P3	A-	A-
P4	GND	GND
P5	B-	B-
P6	B+	B+
P7	GND	GND

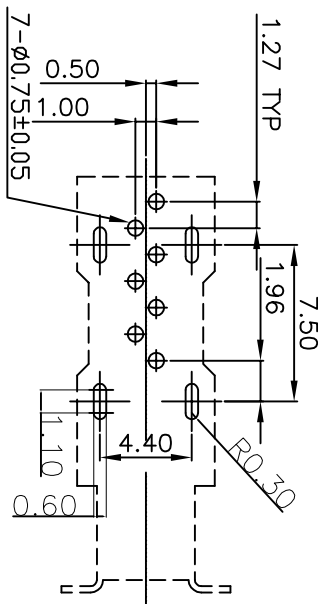
mat'l. code	14	surface	ISO 1302	tolerance	ISO 406	ISO 100	projection	product family	533												
ltr	ecn no	dr	date	ISO 1302	tolerance unless otherwise specified	ISO 406	ISO 100	product family	533												
A	107-1074S	LIN	2007-05-23	angles	.XX±0.25	.XX±0.25	MM	E-SATA_UP_RIGHT													
B	108-1082S	LIN	2008-04-28	linear	.XX±0.25	.XX±0.25	MM	DIP_TYPE													
C	110-0184S	LIN	2010-12-14	linear	.XX±0.100	.XX±0.100	scale 2:1														
D	1-00544QS	LIN	2011-08-31	STERLING	LIN	2007-05-21															
E	2011-10-17	ENG		HKLIM		2016-03-03															
F	2012-06-08	CH		HKLIM		2016-03-03															
G	2016-03-03	DR		KPTAY		2016-03-03															
Sheet	Revision	G	G	107109	111	113	115	117	119	121	123	125	127	129	131	133	135	137	139		
Index	Sheet	1	2	3	106	108	110	112	114	116	118	120	122	124	126	128	130	132	134	136	138



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PIN DEFINITION

ESATA	NAME	TYPE
P1	GND	A+
P2	A+	A-
P3	A-	GND
P4	GND	B-
P5	B-	B+
P6	B+	GND
P7	GND	



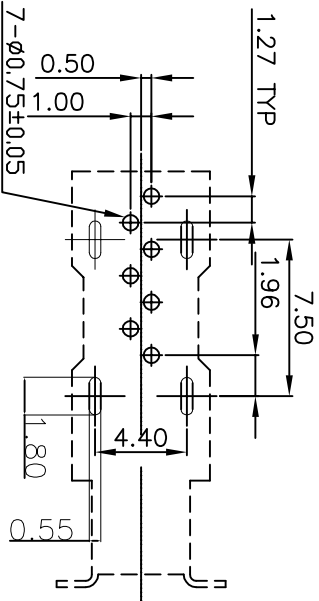
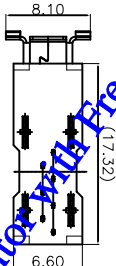
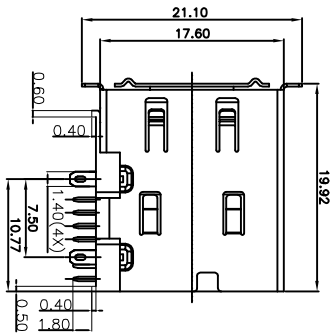
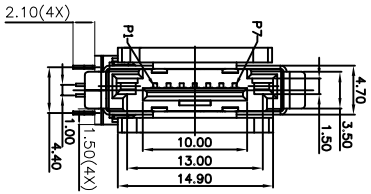
P.C. BOARD MOUNTING DIMENSIONS T=1.60mm  
PCB TOLERANCE: ±0.05

- NOTES:
1. MATERIAL: HOUSING: THERMAL PLASTIC HIGH TEMP WITH 30% G/F U194 V-0 COLOR: BLACK CONTACT: COPPER ALLOY SHELL/BOARD LOCK: COPPER ALLOY
  2. CONTACT: GOLD PLATING ON CONTACT AREA 100µ" MIN. WATT TIN PLATING ON SOLDERMILLS 50µ" MIN. NICKEL UNDERPLATING OVER ALL BOARD LOCK: 50µ" MIN. NICKEL PLATING OVER ALL SHELL/BOARD LOCK: 50µ" MIN. NICKEL PLATING OVER ALL
  3. N/A WAVE SOLDER APPLICATION WITH A 1.5MM P/B
  4. PRODUCT SPEC : GS-12-398
  5. PACKING SPEC : GS-14-1109
  6. PRODUCT NUMBERING: 10074141 - 0 0 0 LF
- PAKING: TRAY PACKING  
LEAD FREE  
1: 15µ" GOLD PLATING  
2: 6/7 GOLD PLATING
6. A SYMBOL  $\Delta$  WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE, WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION

mat'l. code	14	surface	sg	tolerance	projection	product family
lfr	ecm no	dr	date	ISO 1302	ISO 406	ISO 100
A	107-1074S	LIN	2007-05-23	tolerances unless otherwise specified	MM	533
B	108-1082S	LIN	2008-04-28	angle	MM	E-SATA_UP_RIGHT
C	110-0184S	LIN	2010-12-14	line ar	MM	DIP_TYPE
D	T-00544QS	LIN	2011-08-31	σ±Z	SCALE 2:1	
E	EX-S-01187H	HKL	2011-10-17	ENG		
F	EX-S-01187H	HKL	2012-06-08	CH		
G	EX-S-2340H	HKL	2016-03-03	QPP		
Sheet	Revision	G	G	G	107 109 111 113 115 117 119 121 123 125 127 129 131 133 135 137 139	type PRODUCT-CUSTOMER_DWG Drw/wing
Index	Sheet	1	2	3	106 108 110 112 114 116 118 120 122 124 126 128 130 132 134 136 138	sheet 2 of 3 size A3



dwg no 10074141 sheet 2 of 3 size A3



P.C.B. BOARD MOUNTING DIMENSIONS T=1.60mm  
PCB TOLERANCE: ±0.05

PIN DEFINITION	
ESATA	NAME TYPE
	P1 GND
	P2 A+
	P3 A-
	P4 GND
	P5 B-
	P6 B+
	P7 GND

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mat'l. code	14	surface	ISO 1302	ISO 406	ISO 150	100	projection	product family	533												
lfr	ecn no	dr	date	tolerances unless otherwise specified	angles	linear	XXX±0.100	MM													
A	107-1074S	UN	2007-05-23																		
B	108-1082S	UN	2008-04-28																		
C	110-0184S	UN	2010-12-14	0±Z																	
D	T-00544QS	UN	2011-08-31	dr			STERLING	UN	2007-05-24												
E	EX-S-0078R	HKL	2011-10-17	engr			HKLIM		2016-03-03												
F	EX-S-0118R	HKL	2012-06-08	chr			HKLIM		2016-03-03												
G	EX-S-234W	HKL	2016-03-03	dpd			KPTAY		2016-03-03												
Sheet	Revision	1	2	3	107	109	111	113	115	117	119	121	123	125	127	129	131	133	135	137	139
Index	Sheet	G	G	G	106	108	110	112	114	116	118	120	122	124	126	128	130	132	134	136	138

- NOTES:
1. MATERIAL: THERMOPLASTIC HIGH TEMP WITH 30% G/F UL94 V-0
  2. FINISH: CONTACT: COPPER ALLOY; SHELL/BOARD LOCK: COPPER ALLOY
  3. CONTRACT/GOLD PLATING ON CONTACT AREA
  4. BOARD LOCK: 50μ" MIN. NICKEL UNDERPLATING OVER ALL SHELL/BOARD LOCK; 50μ" MIN. NICKEL PLATING OVER ALL
  5. IN A WAVE SOLDER APPLICATION WITH A 1.5MM PCB
  6. PRODUCT SPEC: 05-12-386
  7. PACKING SPEC: 05-14-1109
  8. PRODUCT NUMBERING: 10074141 - 2 0 X X X LF - LEAD FREE
6. A SYMBOL  $\Delta$  WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE, WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION
- 2: LAYOUTS  
1: 15μ" GOLD PLATING  
2: 0.7μ" GOLD PLATING  
PACKING: TRAY PACKING  
BLANK: TRAY PACKING